

Time	Yield (a.u.)
15s	~5.5
5s	~7.5

FIG. 4

2/2

PLASMA POWER (W)	ETCH RATE ($\text{\AA}/\text{min}$)
500	23
700	21
900	18

FIG. 5

TEST	RF BIAS (W)	ETCH CHEMISTRY (sccm)	ETCH RATE ($\text{\AA}/\text{min}$)
A	0	Ar ONLY: 120	46
B	300	Ar ONLY: 120	660
C	0	N ₂ ONLY: 100	454
D	300	N ₂ ONLY: 100	3068
E	0	Ar/N ₂ : 100/20	322
F	100	Ar/N ₂ : 100/20	1280
G	300	Ar/N ₂ : 100/20	2712
H	500	Ar/N ₂ : 100/20	3474

FIG. 6